

IN THE CLAIMS:

Claims 1-41 (Previously Canceled).

42. (Currently Amended) A method for bonding an integrated circuit to a substrate using heat without deforming an adjacent part of said substrate having a color filter bonded thereto and a polarizer bonded onto a face of said color filter opposite said substrate, said substrate comprising an epoxy resin reinforced with fiberglass, said method comprising the steps of:

positioning a face of said integrated circuit adjacent to a face of said substrate with a thermosetting resin between said integrated circuit and said substrate;

supporting an opposite face of said substrate;

positioning a face of a resilient sheet adjacent to an opposite face of said integrated circuit;

positioning a block against an opposite face of said resilient sheet and pressing said block against said resilient sheet to force said integrated circuit toward said substrate;

heating said block to heat said opposite face of said integrated circuit;

applying heat to said opposite face of said substrate concentrated in a region opposite said integrated circuit by irradiating said substrate with near infrared light while avoiding direct heating of said substrate peripheral of said region opposite said color filter and said polarizer, some energy of said light being absorbed by said substrate and some energy of said light passing through said substrate to said resin; and

during the steps of heating said block and applying heat to said opposite face of said substrate, cooling a portion of said resilient sheet peripheral to said integrated circuit adjacent to

said color filter and said polarizer to reduce indirect heating of said color filter and said polarizer from said block via said resilient sheet; wherein the step of cooling comprises the step of discharging a gas against said portion of said resilient sheet peripheral to said integrated circuit adjacent to said color filter and said polarizer.

43. (Currently Amended) A method as set forth in claim 42 wherein ~~said cooling step~~ comprises the step of discharging a gas ~~blowing air~~ against said portion of said resilient sheet peripheral to said integrated circuit adjacent to said color filter and said polarizer comprises the step of discharging said gas toward said block against a surface of said resilient sheet.

44. (Currently Amended) A method as set forth in claim 42 wherein said step of discharging ~~said gas~~ ~~blowing said air~~ comprises the step of discharging said gas ~~blowing said air~~ against a surface of said resilient sheet adjacent to said block.

45. (Previously Presented) A method as set forth in claim 42 wherein said substrate also has another polarizer bonded onto said opposite face of said substrate adjacent to said region of said substrate opposite the first said polarizer; and during the steps of heating said block and applying heat to said opposite face of said substrate, cooling said other polarizer.

46. (Previously Presented) A method as set forth in claim 45 wherein said other polarizer is positioned adjacent to a heat sink, and the step of cooling said other polarizer comprises the steps of blowing air against said heat sink.

47. (Previously Presented) A method as set forth in claim 46 wherein said heat sink has one plate adjacent to said other polarizer, and another plate angled relative to said one plate to shield said plate from heat applied in the step of heating said region of said substrate.

48. (Previously Presented) A method as set forth in claim 46 wherein after the steps of heating said block and applying heat to said opposite face of said substrate, further comprising the step of cooling said block.

49. (Previously Presented) A method as set forth in claim 48 wherein the step of cooling said block comprises the step of flowing a cooling liquid through an opening in said block.

50. (Previously Presented) A method as set forth in claim 42 wherein the step of supporting an opposite face of said substrate comprises the step of supporting said opposite face of said substrate with another block, and after the steps of heating the first said block and applying heat to said opposite face of said substrate, further comprising the step of cooling said other block.

51. (Previously Presented) A method as set forth in claim 50 wherein the step of cooling said other block comprises the step of flowing a cooling liquid through an opening in said other block.

Claims 52-61 are withdrawn pursuant to the restriction requirement.

62. (Currently Amended) A method of forming a bonded assembly, said method comprising the steps of:

positioning an IC chip adjacent to a substrate with a thermosetting adhesive between said IC chip and said substrate to adhere said IC chip to said substrate, a color filter bonded to said substrate and a polarizer bonded to a face of said color filter opposite said substrate, said color filter and said polarizer being adjacent to said IC chip, ~~said substrate comprising an epoxy resin reinforced with fiberglass;~~ and

irradiating said substrate with near infrared light toward said IC chip such that some energy of said light is absorbed by said substrate and some energy of said light passes through said substrate to said adhesive to substantially cure said adhesive; and

wherein the positioning step is performed by positioning a face of said IC chip adjacent to a face of said substrate with said thermosetting adhesive between said face of said IC chip and said face of said substrate, and further comprising the steps of:

supporting an opposite face of said substrate;

positioning a face of a resilient sheet adjacent to an opposite face of said IC chip;

positioning a block against an opposite face of said resilient sheet and pressing said block against said resilient sheet to force said IC chip toward said substrate;

heating said block to heat said opposite face of said IC chip; and wherein the step of irradiating said substrate is performed by applying heat to said opposite face of said substrate concentrated in a region opposite said IC chip, while avoiding direct heating of said substrate peripheral of said region opposite said color filter and said polarizer; and

during the steps of heating said block and applying heat to said opposite face of said substrate, cooling a portion of said resilient sheet peripheral to said IC chip adjacent to said color

filter and said polarizer to reduce indirect heating of said color filter and said polarizer from said block via said resilient sheet; wherein the step of cooling comprises the step of discharging a gas against said portion of said resilient sheet peripheral to said integrated circuit adjacent to said color filter and said polarizer.

Please enter new claims 63-64 as follows:

63. (New) A method as set forth in claim 62 wherein the step of discharging gas against said portion of said resilient sheet peripheral to said integrated circuit adjacent to said color filter and said polarizer comprises the step of discharging said gas air toward said block against a surface of said resilient sheet adjacent to said block.

64. (New) A method as set forth in claim 62 wherein said step of discharging said gas comprises the step of discharging said gas against a surface of said resilient sheet adjacent to said block.